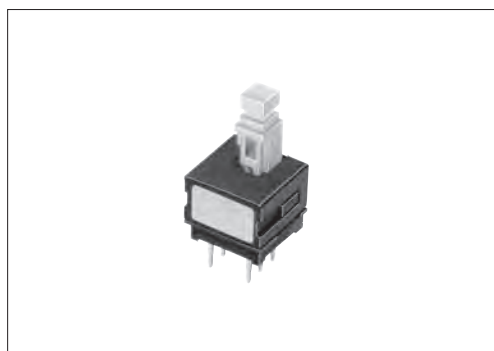


SPPH1 1.5mm-travel Vertical Type

Vertical push switch with two types of knob available



Typical Specifications



Items		Specifications
Rating (max.)/(min.) (Resistive load)		0.1A 30V DC / 50μA 3V DC
Contact resistance (Initial/After operating life)		20mΩ max. / 40mΩ max.
Operating force		Refer to the products line
Operating life	Without load	10,000 cycles
	With load	10,000 cycles (0.1A 30V DC)

Product Line

Product Line															
Changeover timing	Travel (mm)	Total travel (mm)	Mounting method	Poles	knob style	Operating force	Operation	Terminal type	Minimum order unit (pcs.)		Product No.	Drawing No.			
									Japan	Export					
Non shorting	1.5	2.5	PC board	2	Standard	$2 \begin{smallmatrix} +1 \\ -0.7 \end{smallmatrix} \text{ N}$	Latching	Straight	800	4,000	SPPH110800	1			
							Momentary				SPPH110300				
					Short		Latching				SPPH120400	2			
							Momentary				SPPH120100				
					Standard		Latching	Snap-in			SPPH130400	1			
							Momentary				SPPH130100				
					Short		Latching				SPPH140300	2			
							Momentary				SPPH140100				
					Standard	$3 \begin{smallmatrix} +1 \\ -0.7 \end{smallmatrix} \text{ N}$	Latching	Straight			SPPH110900	1			
							Latching				SPPH130500				
					Short		Latching	Snap-in			SPPH140400	2			
							Latching				SPPH140400				

Packing Specifications

Bulk

Number of packages (pcs.)		Export package measurements (mm)
1 case / Japan	1 case / export packing	
800	4,000	400×270×290

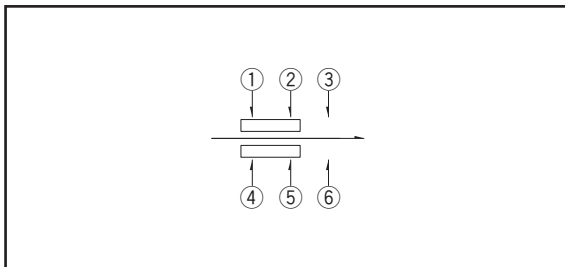
Refer to P.130 for soldering conditions.

■ Dimensions

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the direction A)	
1		Straight terminal	Snap-in terminal
2		Straight terminal	Snap-in terminal












■ Circuit Diagram (Viewed from Direction A)



■ Terminal Configuration

Unit:mm

Straight terminal	Snap-in terminal
--------------------------	-------------------------

Series			Vertical			
			SPEH	SPEJ	SPPH4	SPPH1
Photo						
Dimensions (mm)	W		6	7	6.5	10
	D		6	7	8.5	10
	H		5	5.95	8.5	
Travel (mm)			—	—	2.2	1.5
Total travel (mm)			1.6	1.7	3	2.5
Number of poles			1	2		
Operating temperature range			−40℃ to +90℃	−40℃ to +85℃	−10℃ to +60℃	
Automotive use					—	
Life cycle						
Rating (max.) (Resistive load)			50mA 16V DC	0.2A 14V DC	0.1A 30V DC	
Rating (min.) (Resistive load)			10μA 1V DC	—	50μA 3V DC	
Durability	Operating life without load		100,000cycles 400mΩ max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.
	Operating life with load (at max. rated load)		100,000cycles 400mΩ max.	10,000cycles 150mΩ max.	10,000cycles 100mΩ max.	10,000cycles 40mΩ max.
Electrical performance	Initial contact resistance		200mΩ max.	150mΩ max.	100mΩ max.	20mΩ max.
	Insulation resistance		100MΩ min. 100V DC	100MΩ min. 500V DC		
	Voltage proof		250V AC for 1minute	500V AC for 1minute		
Mechanical performance	Terminal strength		—	—	5N for 1minute	
	Actuator strength	Operating direction	50N	49N	30N	50N
		Pulling direction	—	—	10N	—
Environmental performance	Cold		−40℃ 1000h	−40℃ 500h	−20℃ 96h	
	Dry heat		90℃ 1000h	85℃ 500h	85℃ 96h	
	Damp heat		60℃, 90 to 95%RH 1000h	60℃, 90 to 95%RH 500h	40℃, 90 to 95%RH 96h	
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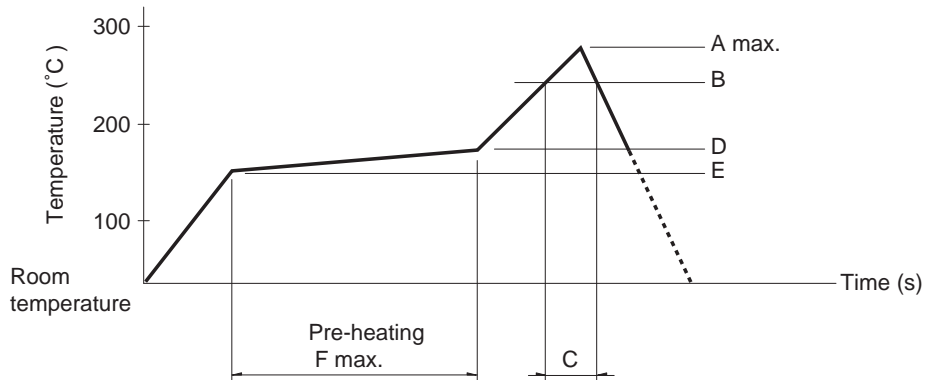
Push Switches Soldering Conditions	130
Push Switches Cautions	131

Note

● Indicates applicability to all products in the series.

Example of Reflow Soldering Condition

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple ϕ 0.1 to 0.2 CA (K) or CC (T) at soldering portion (copper foil surface).
A heat resisting tape should be used for fixed measurement.
3. Temperature profile



Series (Reflow type)	A (°C) 3s max.	B (°C)	C (s)	D (°C)	E (°C)	F (s)
SPEJ	260	230	40	180	150	120
SPEF						
SPEH						

Notes

1. The condition mentioned above is the temperature on the mounting surface of a PC board. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the PC board's material, size, thickness, etc.
The above-stated conditions shall also apply to switch surface temperatures.
2. Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

Reference for Hand Soldering

Series	Soldering temperature	Soldering time
SPPJ3, SPPJ2, SPUN, SPUJ, SPPH4, SPPH1	350±10°C	3+1/0s
SPED2, SPED4	350±10°C	3±0.5s
SPEJ	350±10°C	4s max.
SPEF	350±5°C	3s max.
SPEH	350°C max.	3s max.

Reference for Dip Soldering

(For PC board terminal types)

Series	Items		Dip soldering	
	Preheating temperature	Preheating time	Soldering temperature	Duration of immersion
SPPJ3	100°C max.	60s max.	260±5°C	5±1s
SPUN	100°C max.	60s max.	260±5°C	10±1s
SPUJ, SPPH4	—		260±5°C	5±1s
SPPJ2, SPPH1, SPED2, SPED4, SPEF	—		260±5°C	10±1s